

**METHOD AND APPARATUS FOR ATTACHING A PROCESSOR AND
CORRESPONDING HEAT SINK TO A CIRCUIT BOARD**

Abstract of Disclosure

[0029] An apparatus for attaching a processor and corresponding heat sink to a circuit board includes a board member, a frame member mounted on the board member, a plurality of connector portions on the frame member, and a resilient load member. The resilient load member has a first end moveably connected to one of the connector portions and a second end forcibly connected to another one of the connector portions. A processor socket is mounted on the board member and a processor is seated in the processor socket. Forcible connection of the second end to its connector portion deforms the load member into engagement with the processor and urges the processor into the processor socket. A heat sink is mounted to the frame member and in thermal contact with the processor.